Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

Name / Model #1 : Compaq S1922a LCD Monitor
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>2</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>SCREW DRIVER(PHILLIPS HEAD)</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. External Electric Cables Dissecting Process
2. Remove Stand Base From Display
3. Remove Rear Cover From Display Head
4. Remove Mainframe &Panel
5. Remove Front Cover From Display Head
6. Take Screw off From Power Bd & Main Bd Remove Mainframe
7. Take Speaker off From Mainframe
8. Disassembly Stand&Base

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP- S1922a Disassembly Process

IE
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1. Remove Cable From Display Head.

2. Dissecting To Complete.
Remove Stand Base From Display

1. Take Screw From Stand.
2. Remove Stand.

2. Turn around the monitor

3. Remove Rear Cover.
Remove Mainframe & Panel

1. Take KEPC board off from the Front Cover

2. Remove Connector off from KEPC board.

3. Remove Connector off from Power board.

4. Remove Connector off from Panel.
Remove Mainframe & Panel

1. Remove the Conductive Tape (Right)
2. Remove the Conductive Tape (Underside)
3. Remove the Mainframe.
Remove Front Cover From Display Head

1. Turn around the panel

2. Remove the Front Cover from panel
Take Screw off From Power Bd & Main Bd
Remove Mainframe

1. Take screw(*2) off from Mainboard.

2. Take screw(*4) off from Mainframe.

3. Remove Connector off from Main board.
Take Screw off From Power Bd & Main Bd
Remove Mainframe

1. Remove Connector off from Power board.

2. Take the power board off from Mainframe.
Take Speaker off From Mainframe

1. Take the speaker off from Mainframe.
Disassembly Stand & Base

1. Take the Stand off from the Base.

2. Take the Middle Stand off from the Stand.
Disassembly Stand & Base

1. Take screw(*3) off from Stand.

2. Take the hinge off from Stand.